

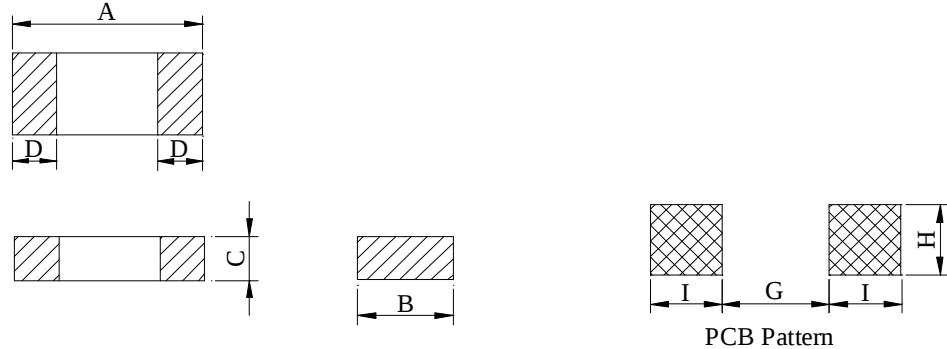
SPECIFICATION FOR APPROVAL

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PROD. NAME	MULTILAYER CHIP BEAD	ABC'S DWG NO.	MU1005□□□□L□-□□□
		ABC'S ITEM NO.	

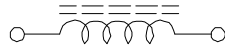
I . CONFIGURATION & DIMENSIONS :



Unit : m/m

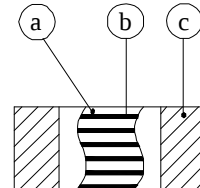
Series	A	B	C	D	G	H	I
MU1005	1.00±0.10	0.50±0.10	0.50±0.10	0.20±0.10	0.4	0.4	0.5

II . SCHEMATIC DIAGRAM :



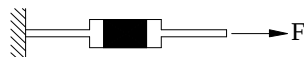
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal electrode : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

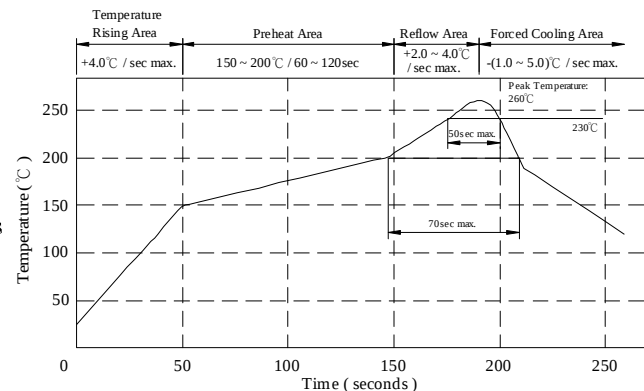
- a . Storage temp. : -40 --- +105℃
- b . Operating temp. : -55 --- +125℃
- c . Terminal strength :



Type	F (kgf)	Time (sec)
MU1005	0.3	30±5

- d . Solderability : Preheat : 150±25℃ for 60 seconds
Solder : Sn96.5 / Ag3 / Cu0.5
or equivalent
Solder temp. : 260±5℃
Flux : Rosin
Dip time : 4±1 seconds

Peak Temp : 260℃ max.
Max time above 230℃ : 50sec max.
Max time above 200℃ : 70sec max.



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V . ELECTRICAL CHARACTERISITCS :

DWG No.	Impedance (Ω) At 100MHz	DC Resistance (Ω) max	Rated Current (mA) max
MU1005300YL□-□□□	30.0±25 %	0.30	500
MU1005600YL□-□□□	60.0±25 %	0.40	200
MU1005121YL□-□□□	120.0±25 %	0.50	200
MU1005221YL□-□□□	220.0±25 %	0.70	100
MU1005301YL□-□□□	300.0±25 %	0.80	100
MU1005451YL□-□□□	450.0±25 %	0.90	100
MU1005601YL□-□□□	600.0±25 %	1.00	100

1). □ : Packaging Information... ☐A : Bulk ☐B : Taping Reel

2)."- □□□ " :Reference code



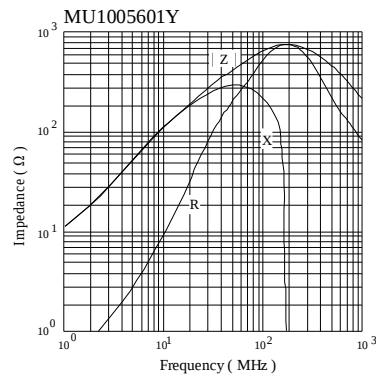
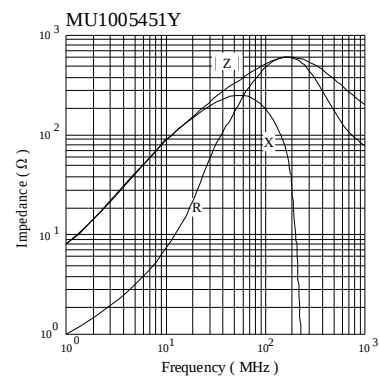
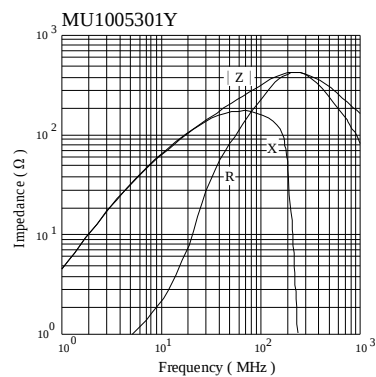
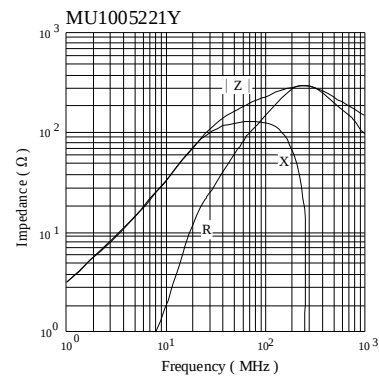
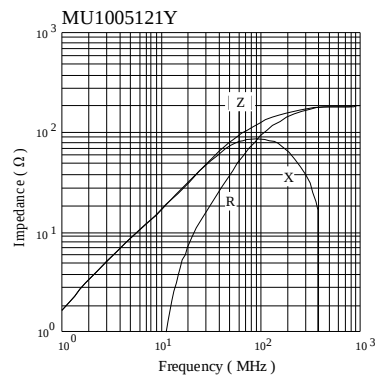
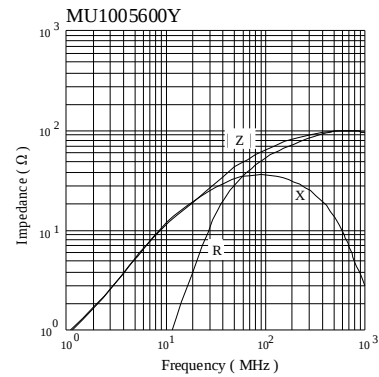
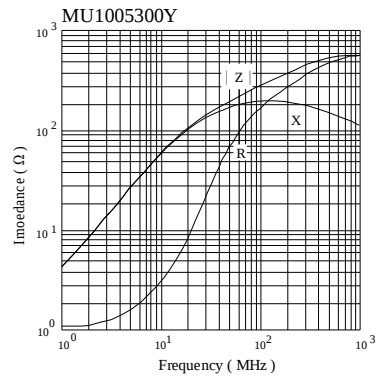
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VI . IMPEDANCE VS. FREQUENCY RESPONSE CURVE :



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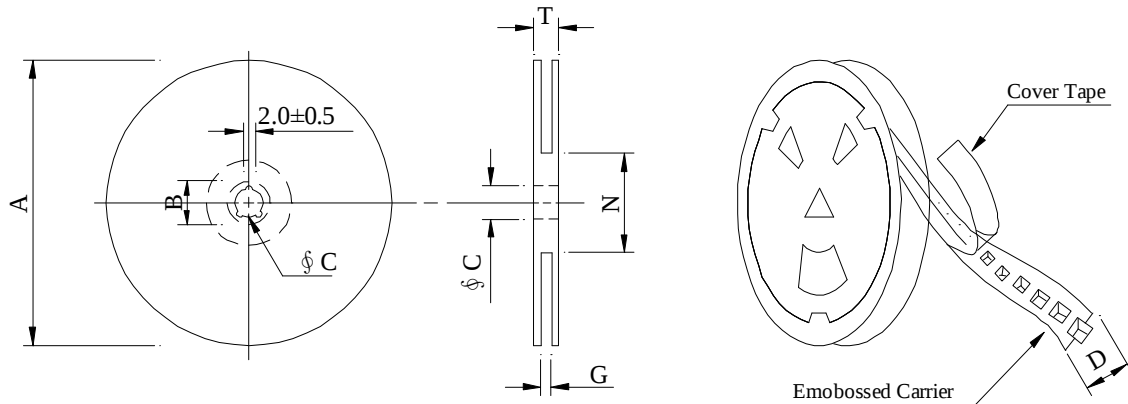
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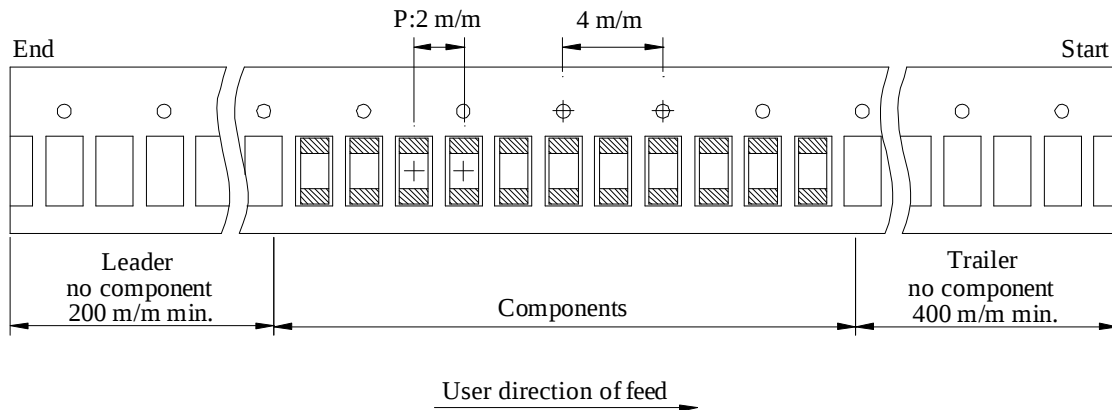
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VII . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	QTY (pcs)	G.W. (gw)	Style	QTY(kpcs)	G.W. (Kg)	Size (cm)
MU1005	10,000	60	07 - 08	500	5.5	42 x 41 x 24

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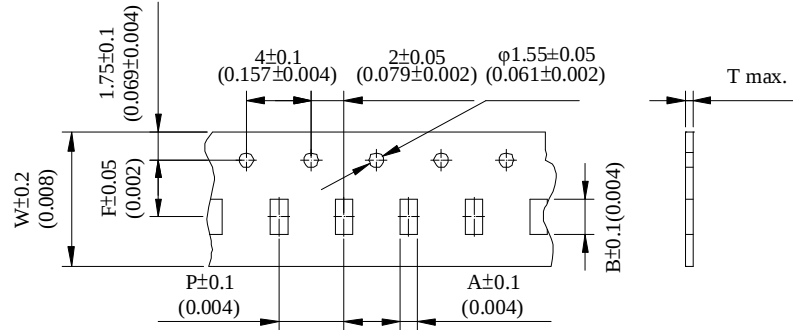
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(4) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MU1005	0.65	1.15	3.50	2.0	0.80	8.0	1

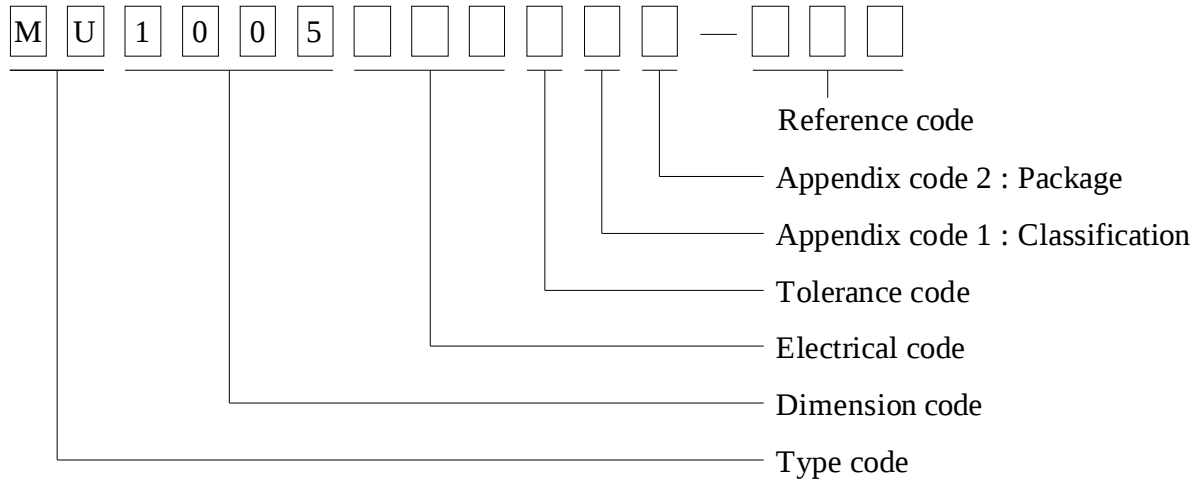
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VIII . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

L : Lead Free Standard products comply with RoHS' requirements

1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package Q'TY	Remark
A	T.B.D.	T.B.D.	
B	T / R (Reel package)	10000 pcs	

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